

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	34154	semiconductor and (electrical adj connection)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:20
2	BRS	L2	6794	1 and die	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 10:17
3	BRS	L3	2263	2 and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:20
4	BRS	L4	3	3 and (first adj contact adj site) and (second adj contact adj site)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	40	3 and (first adj face) and (second adj face)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 11:49
6	BRS	L7	440	1 and (receiv\$3 with die) and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 13:04
7	BRS	L10	944	1 and 438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:13
8	BRS	L11	62	7 and 438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 12:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L12	215	1 and (bond adj pad) and (receiv\$3 with die) and ((flip adj chip) or wirebond\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 13:05
10	BRS	L13	5888	438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:24
11	BRS	L14	20821	semiconductor and die and ((flip adj chip) or wire\$7)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:25
12	BRS	L15	5888	438/108,106,121,612,669.ccls.	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
13	BRS	L16	1055	438/108,106,121,612,669.ccls. and semiconductor and die and ((flip adj chip) or wire\$7)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:47
14	BRS	L17	971	16 and pack\$5	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:48
15	BRS	L18	583	438/108,106,121,612,669.ccls. and semiconductor and die and ((flip adj chip) or wirebond)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:22
16	BRS	L19	549	18 and pack\$5	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:48

	Type	L #	Hits	Search Text	DBs	Time Stamp
17	BRS	L20	112	19 and (bottom adj surface) and (top adj surface)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 14:54
18	BRS	L21	144	438/108,106,121,612,669.ccls. and semiconductor and die and (flip adj chip) and (wire adj bond)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:23
19	BRS	L22	72	438/108,106,121,612,669.ccls. and semiconductor and die and (flip adj chip) and (wire adj bond) and (electric\$3 adj connection)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/12 15:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	126270 1	semiconductor	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 15:46
2	BRS	L2	353	438/108,109,123,617.ccls. and ((flip adj chip) same wire\$5)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 15:48
3	BRS	L3	253	438/108,109,123,617.ccls. and ((flip adj chip) with wire\$5)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 15:51
4	BRS	L4	269	438/108,109,123,617.ccls. and ((flip adj chip) with wire\$7)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 15:55

	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L7	269	438/108,109,123,617.ccls. and ((flip adj chip) with (wire\$7 or (wire adj bond\$3)))	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 15:56
6	BRS	L6	195	4 and ((lead adj frame) or die)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 16:01
7	BRS	L8	195	4 and ((lead adj frame) or die)	USPAT ; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/16 16:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	22	(438/108,109,123,617.ccls. and ((flip adj chip) with (wire adj bond))) and ((lead adj frame) or die) and (interconnect or connect\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 10:59
2	BRS	L2	61	(257/666,676,692,778,784,686.ccls. and ((flip adj chip) with (wire adj bond))) and ((lead adj frame) or die) and (interconnect or connect\$3)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 12:16
3	BRS	L3	61	(257/666,676,692,778,784,686.ccls. and ((flip adj chip) with (wire adj bond))) and ((lead adj frame) or die) and \$5connect\$3	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 14:30
4	BRS	L4	1	(257/666,676,692,778,784,686.ccls. and ((flip adj chip) with (wire adj bond))) and ((lead adj frame) or die) and \$5connect\$3 and ((known adj good adj die) or KGD)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 14:35



	Type	L #	Hits	Search Text	DBs	Time Stamp
5	BRS	L5	2	(438/108,109,123,617.ccls. and ((flip adj chip) with (wire adj bond))) and ((lead adj frame) or die) and \$5connect\$3 and ((known adj good adj die) or KGD)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 14:34
6	BRS	L6	2	438/108,109,123,617.ccls. and ((flip adj chip) with (wire adj bond)) and \$5connect\$3 and ((known adj good adj die) or KGD)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 14:34
7	BRS	L7	25	((flip adj chip) with (wire adj bond)) and \$5connect\$3 and ((known adj good adj die) or KGD)	USPAT; US-PG PUB; EPO; JPO; DERW ENT; IBM_T DB	2003/09/17 14:36